LMH1218EVM Evaluation Board

User's Guide

Literature Number: SNLU173A
January 2015–Revised March 2015

1 Overview

The LMH1218EVM evaluation module provides a complete high bandwidth platform to evaluate the SDI/UHD and 10 GbE signal conditioning features of the Texas Instruments LMH1218 UHD Cable Driver with Integrated Reclocker. The LMH1218EVM can be used for standard compliance testing, performance evaluation, and initial system prototyping. The SMA and BNC edge launch connectors used for the LMH1218EVM will interface to multiple system connector types via commercially available breakout cables, adaptors, and boards (not included). This flexible connectivity enables integrated system level testing between TI's 12G SDI Cable Driver with Reclocker and 3rd party ASIC/FPGA host boards. A graphical user interface can be used to manage LMH1218 device registers.

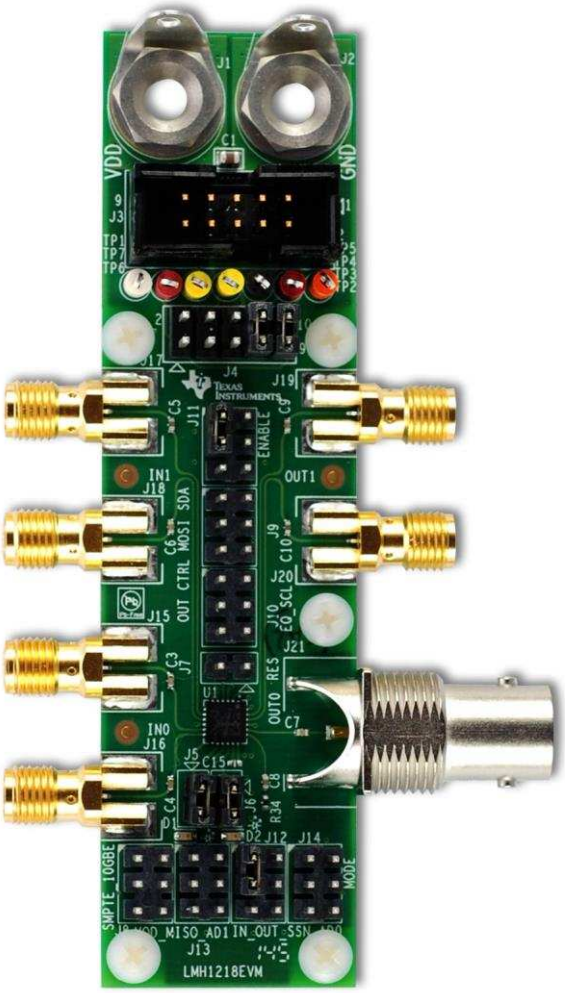


Figure 1. LMH1218EVM

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2 Features

- Locks to standard SDI (2.97 Gbps, 1.485 Gbps, or divide-by-1.001 sub-rates), DVB-ASI (270 Mbps), ST-2081 (5.94 Gbps proposed), ST-2082 (11.88 Gbps proposed), and 10 GbE data rates
- Integrated 2:1 100 Ω mux on input and 1:2 fan-out (one 75 Ω and one 100 Ω) output drivers with de-emphasis supporting dual media (coax and fiber)
- Programmable by SPI or SMBus interface
- 100 Ω differential and 75 Ω single-ended output drivers with de-emphasis
- Single supply operation: VDD = 2.5 V ± 5%
- High speed signal flow–thru pin-out package: 24-pin QFN (4 mm x 4 mm, 0.5 mm pitch)
- GUI platform to support fast bring-up during product development
- -40°C to +85°C Operation

3 Applications

- UHDTV/4K/8K/HDTV/SDTV Video
- Digital Video Routers and Switches
- Digital Video Processing and Editing
- DVB-ASI
- Distribution Amplifiers

4 Ordering Information

Table 1. LMH1218EVM Ordering Information

EVM ID	DEVICE ID	DEVICE PACKAGE
LMH1218EVM	LMH1218RTW	RTW0024A

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5 Setup

This section describes the jumpers and connectors on the EVM as well as how to connect, set up, and use the LMH1218EVM. When operating the LMH1218EVM, signal inputs and outputs can be connected as shown in Figure 2.

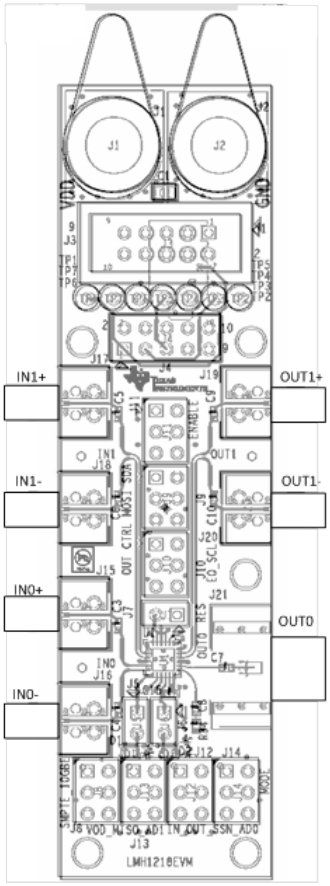


Figure 2. LMH1218EVM Input and Output Pins

Table 2. Input and Output Channel Connectors

JUNCTION NUMBERS	FUNCTION
J15, J16	IN0+, IN0- (SMA)
J17, J18	IN1+, IN1- (SMA)
J19, J20	OUT1+, OUT1- (SMA)
J21	OUT0+ (BNC Single-Ended)

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5.1 Modes of Operation

The LMH1218EVM can be used in one of two modes:

1. **SPI Mode** – Provides full access to the LMH1218 status and control settings via MISO, MOSI, SCK, and SS_N pins.
2. **SMBus Mode** – Provides full access to the LMH1218 status and control settings via SDA, SCL, and GND pins. ADDR0 and ADDR1 pins are used for SMBus address strap.

Using either of these two modes, users have full access to all register controls for greater control of LMH1218 parameters. For convenient use with the USB2ANY controller, LMH1218EVM provides a direct connection via the J3 pin header for the ribbon cable interface. The USB2ANY interface is shown in Figure 3.



Figure 3. USB2ANY Interface for LMH1218EVM SPI and SMBus Control

The external control pins on the LMH1218EVM are used to configure device settings. A 4-level input scheme has been implemented across the control pin interface to increase the amount of control available to the device with fewer physical pins.

The channel settings and controls are configurable for the LMH1218 4-logic levels (0, R, F, 1). The four logic levels correspond to the following voltages in Table 3.

Table 3. Description of 4-Level Voltage Inputs

LEVEL	SETTING	INTERNAL PIN VOLTAGE (2.5 V MODE)
0	Tie 1 kΩ to GND	0.08 V
R	Tie 20 kΩ to GND	1/3 x VDD
F	Float (Leave Pin Open)	2/3 x VDD
1	Tie 1 kΩ to VDD	VDD – 0.04 V

Typical 4-Level Input Thresholds:

- Internal Threshold between 0 and R = 0.2 * VDD
- Internal Threshold between R and F = 0.5 * VDD
- Internal Threshold between F and 1 = 0.8 * VDD

In order to set these 4-level voltage inputs, each input is controlled by a group of 6 jumper pins set in accordance with Figure 4.

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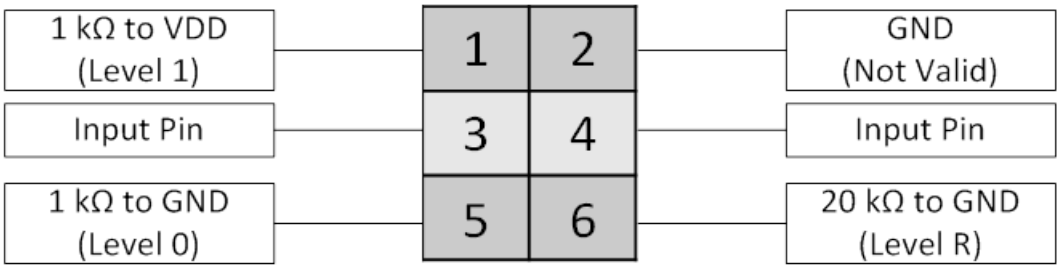


Figure 4. Jumper Orientation for User Configuration

Therefore, the following jumper positions allow access to each of the four logic levels:

Table 4. Jumper Positions

LEVEL	JUMPER TIES
0	Pin 3-5
R	Pin 4-6
F	Pin 3-4 (or no connect)
1	Pin 1-3

The following jumpers are used to set the input condition for 4-level inputs:

J8, J9, J10 J11, J12, J13, J14

In SPI and SMBus modes, the jumpers on the LMH1218EVM control different functions. See Table 5 and Table 6 for jumper descriptions and differences.

Table 5. Description of Connections in SPI Mode (J14 MODE_SEL = Level 1)

COMPONENT	NAME	DESCRIPTION
J1	VDD	2.5 V power supply
J2	GND	GND power supply
J3	SPI Access	Optional SMBus or SPI access pins. See datasheet and EVM schematic for additional operation information.
J4	SPI Access	3.3 V to 2.5 V level shift. Install shunt jumpers on Pins 1-2, 3-4, and 5-6 for proper operation. Do not install shunt jumpers on Pins 7-8 and 9-10.
J5	LOS_INT_N	Default mode: LOS status indicator Programmable interrupt caused by change in LOS, violation of internal eye monitor threshold, or change in lock. External 4.7 kΩ pull-up resistor is required.
J6	LOCK	Signal Lock status. Connect jumper across J6 for Signal Lock status indicator on LED D2. LED turns green when the LMH1218 reclocker is locked.
J7	RES1	Reserved pin. Leave as no connect for normal operation.
J8	SMPTE_10GbE	Level F: Leave open for normal operation
J9	MOSI	SPI Master Output / Slave Input (Leave as Float and use J3 for access if using USB2ANY)
J10	SCK	SPI Serial Clock Input (Leave as Float and use J3 for access if using USB2ANY)
J11	ENABLE	Level 1: Power down until signal is detected Level 0: Power down including signal detects. Reset registers upon power-up
J12	SS_N	SPI Slave Select. This pin has an internal pull-up. (Leave as Float and use J3 for access if using USB2ANY)

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Table 5. Description of Connections in SPI Mode (J14 MODE_SEL = Level 1) (continued)

COMPONENT	NAME	DESCRIPTION
J13	MISO	SPI Master Input / Slave Output (Leave as Float and use J3 for access if using USB2ANY)
J14	MODE_SEL	Level 1: SPI Mode

Table 6. Description of Connections in SMBus Mode (J14 MODE_SEL = Level 0)(1)

COMPONENT	NAME	DESCRIPTION
J3	SMBus Access	Optional SMBus or SPI access pins. See datasheet and EVM schematic for additional operation information.
J4	SMBus Access	External 2 kΩ pull-up resistor to 3.3 V supply. Install shunt jumpers on Pins 7-8 and 9-10 for proper operation. Do not install shunt jumpers on Pins 1-2, 3-4, and 5-6.
J5	LOS_INT_N	Default mode: LOS status indicator Programmable interrupt caused by change in LOS, violation of internal eye monitor threshold, or change in lock. External 4.7 kΩ pull-up resistor is required.
J9	SDA	SMBus Data Input / Output Open Drain. (Leave as Float and J3 for SMBus access if using USB2ANY)
J10	SCL	SMBus Clock Input / Output Open Drain. (Leave as Float and J3 for SMBus access if using USB2ANY)
J12	AD0	4-Level strap pins to determine up to 16 unique SMBus address with J13 to create AD[1:0].
J13	AD1	4-Level strap pins to determine up to 16 unique SMBus address with J12 to create AD[1:0].
J14	MODE_SEL	Level 0: SMBus Mode

(1) Jumpers not listed in Table 6 are identical to the functions mentioned in Table 5.

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6 Quick Start Guide

6.1 SPI and SMBus Control Mode

1. Connect J1: VDD = 2.5 V and J2: GND.
2. Set the jumpers for SPI or SMBus mode as shown below:
   - Tie J5 jumper pins 1-2 and J6 jumper pins 1-2 to use LEDs D1 and D2 as status indicators of LOS and LOCK, respectively.
   - Tie J11 jumper pins 1-3 to enable normal operation by powering up the device when a signal is detected on the selected input channel.
   - For SPI Mode:
     - Tie J14 jumper pins 1-3.
     - **Note:** Tie J4 jumper pins 1-2, 3-4, and 5-6 for SPI 3.3 V to 2.5 V level shift.
   - For SMBus Mode:
     - Tie J14 jumper pins 3-5.
     - **Note:** If SMBus controller does not have pull-ups provided internally for SDA and SCL, tie J4 jumper pins 7-8 and 9-10 to enable on-board 2 kΩ external pull-up resistors to 3.3 V.
     - **Note:** Tie J12 (ADDR0) jumper pins 3-5 and J13 (ADDR1) jumper pins 3-5 for slave address = 0x1A (8-bits). For all other SMBus slave addresses, refer to the LMH1218 datasheet.
   - The jumper configuration for SPI and SMBus mode can be seen in Figure 5 and Figure 6, respectively.

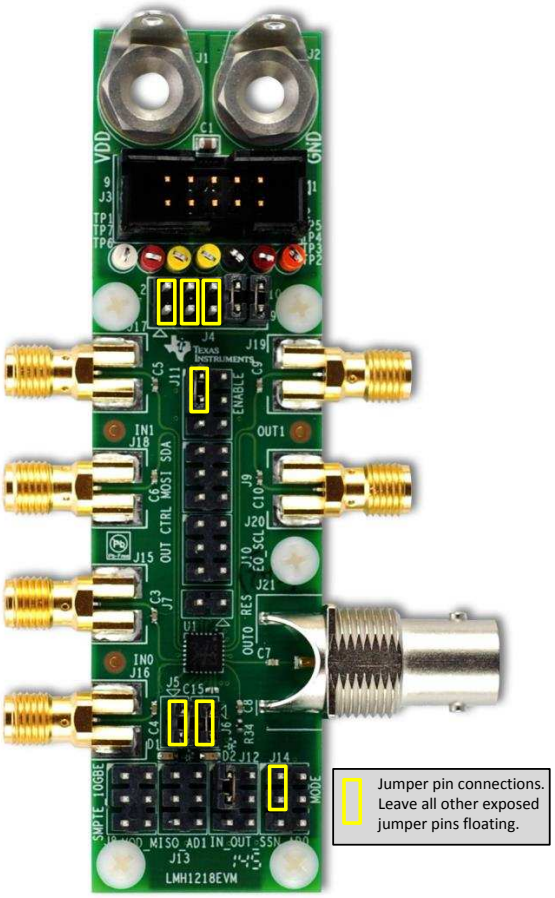


Figure 5. Jumper Pin Configuration for SPI Mode

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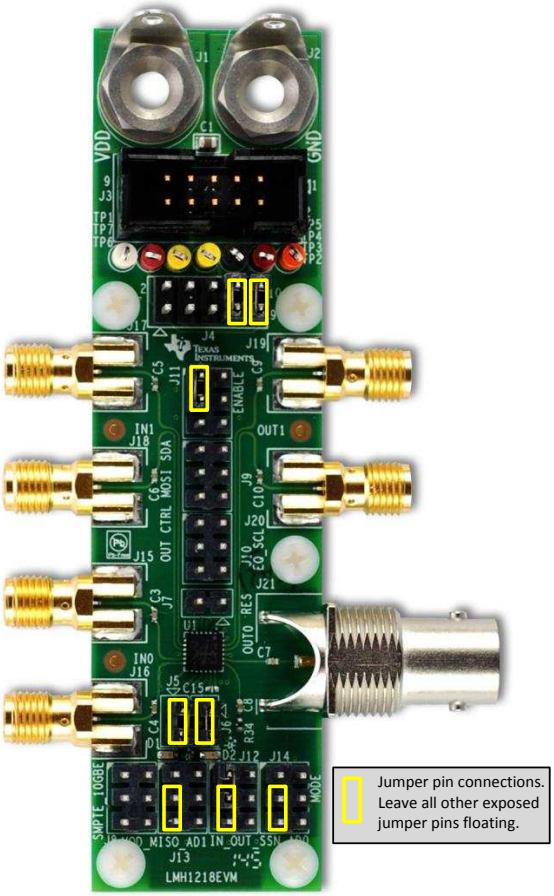


Figure 6. Jumper Pin Configuration for SMBus Mode

- The user is expected to use a USB2ANY ribbon cable to establish SPI or SMBus interface connection via the J3 jumper header. There are multiple ways to access and monitor SPI or SMBus pins on the LMH1218EVM. The following table describes the connection description to access the relevant SPI mode pins:

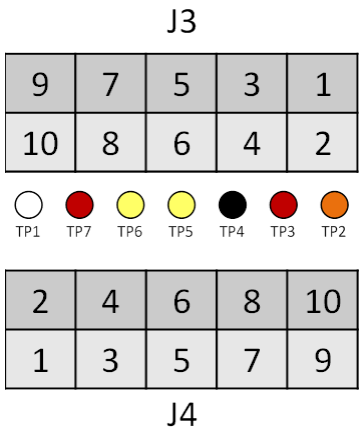


Figure 7. Labeled Diagram of SPI and SMBus Mode Connections

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Table 7. SPI Mode Connections for J3, J4, and TP(1)

FUNCTION	J3 PIN	J4 PIN	TP PIN (TEST POINT)
SS_N	2	2	1
MISO	3	N/A	2
MOSI	4, 10	4, 7	3
SCK	8, 9	6	5
3P3V (3.3 V power)(2)	5	8, 10	N/A
GND	6	N/A	4

(1) TP access pins are not populated on-board during EVM manufacturing.
(2) 3P3V is provided by the USB2ANY module.

Table 8. SMBus Mode Connections for J3, J4, and TP(1)

FUNCTION	J3 PIN	J4 PIN	TP PIN (TEST POINT)
AD0	2	2	1
AD1	3	N/A	2
SDA	4, 10	4, 7	3
SCL	8, 9	6	5
3P3V (3.3 V power)(2)	5	8, 10	N/A
GND	6	N/A	4

(1) TP access pins are not populated on-board during EVM manufacturing.
(2) 3P3V is provided by the USB2ANY module.

3. Connect 50 Ω SMA or 75 Ω cables to the board depending on connector type:
   - Connect an input signal to J17 and J18 for IN1 and J15 and J16 for IN0.
   - The output signals on J19 and J20 are 100 Ω differential and can be connected to a scope or other 100 Ω receiver. The output signal on J21 is 75 Ω single-ended and can be connected via BNC connector to a video analyzer or other 75 Ω instrument.

For further information about operation modes and LMH1218 functions and capabilities when using the LMH1218EVM, please refer to the LMH1218 datasheet.

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7 Example Waveforms

7.1 Alignment Jitter and Rise / Fall Time Performance

Figure 8 to Figure 12 show the output jitter performance of OUT0 under the following conditions:

- Input Signal Pattern: PRBS-15
- VID: 800 mVp-p
- Measured Alignment Jitter (AJ) with scope filter applied
- Measured Rise / Fall Time (Tr / Tf) at 20 / 80
- VDD = 2.5 V, T = 25°C

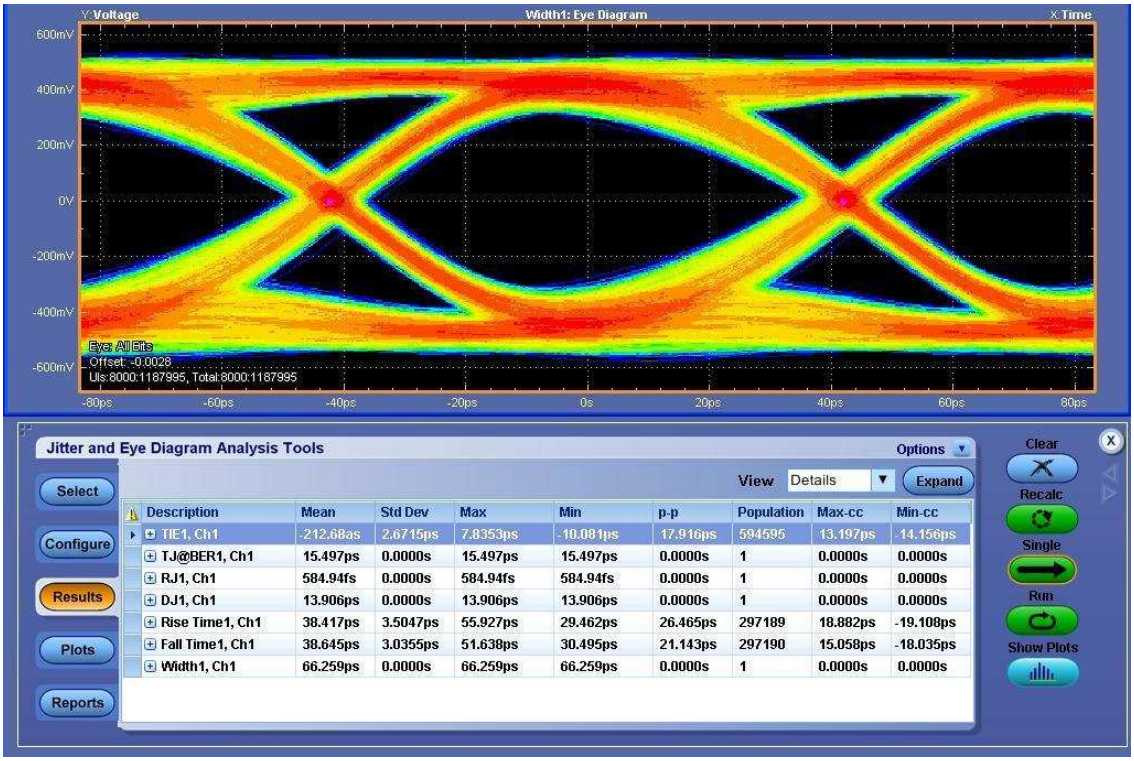


Figure 8. OUT0 (75 Ω) Alignment Jitter (AJ) and Rise / Fall Time at 11.88 Gbps AJ = 15.497 ps, Tr / Tf = 38.417 / 38.645 ps

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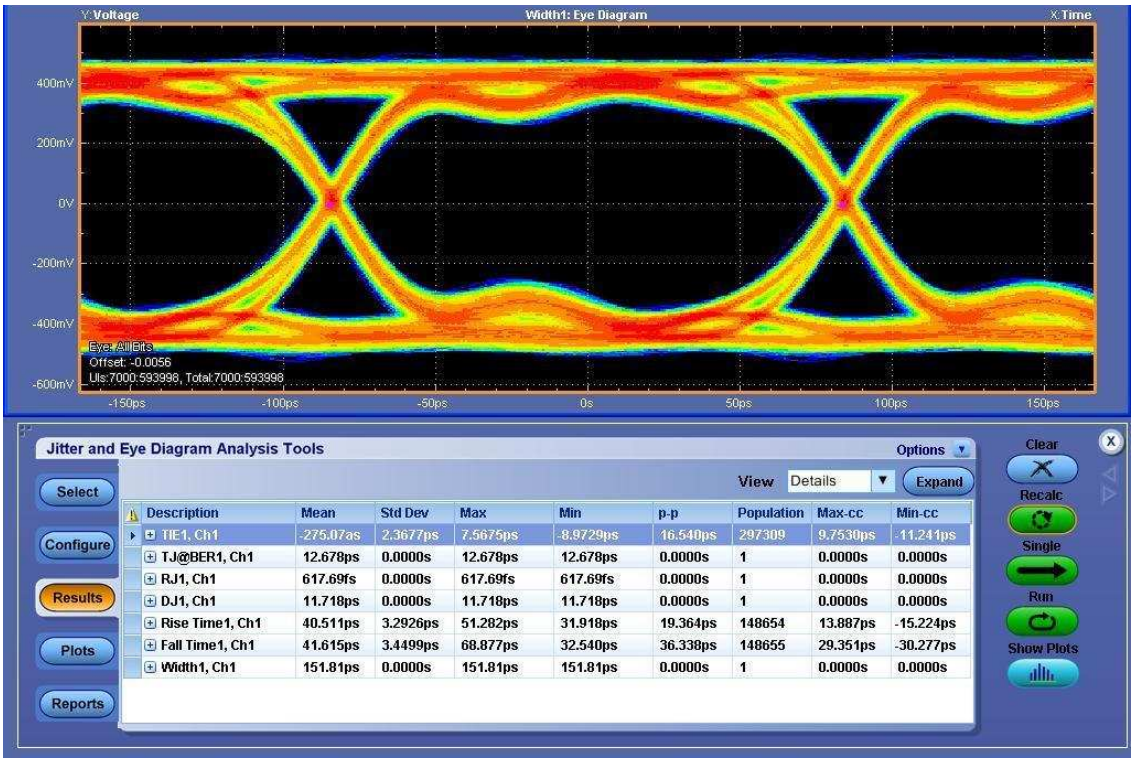


Figure 9. OUT0 (75 Ω) Alignment Jitter (AJ) and Rise / Fall Time at 5.94 Gbps
AJ = 12.678 ps, Tr / Tf = 40.511 / 41.615 ps

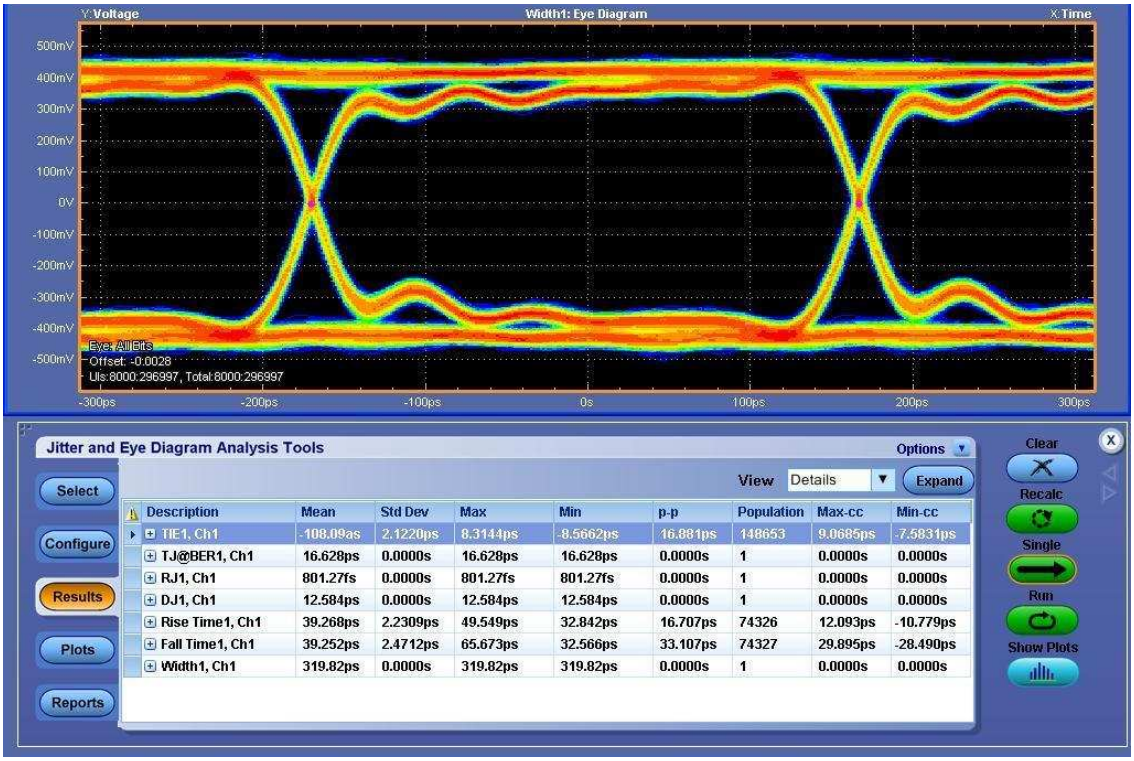


Figure 10. OUT0 (75 Ω) Alignment Jitter (AJ) and Rise / Fall Time at 2.97 Gbps
AJ = 16.628 ps, Tr / Tf = 39.268 / 39.252 ps

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Figure 11. OUT0 (75 Ω) Alignment Jitter (AJ) and Rise / Fall Time at 1.485 Gbps
AJ = 28.208 ps, Tr / Tf = 39.314 / 40.795 ps

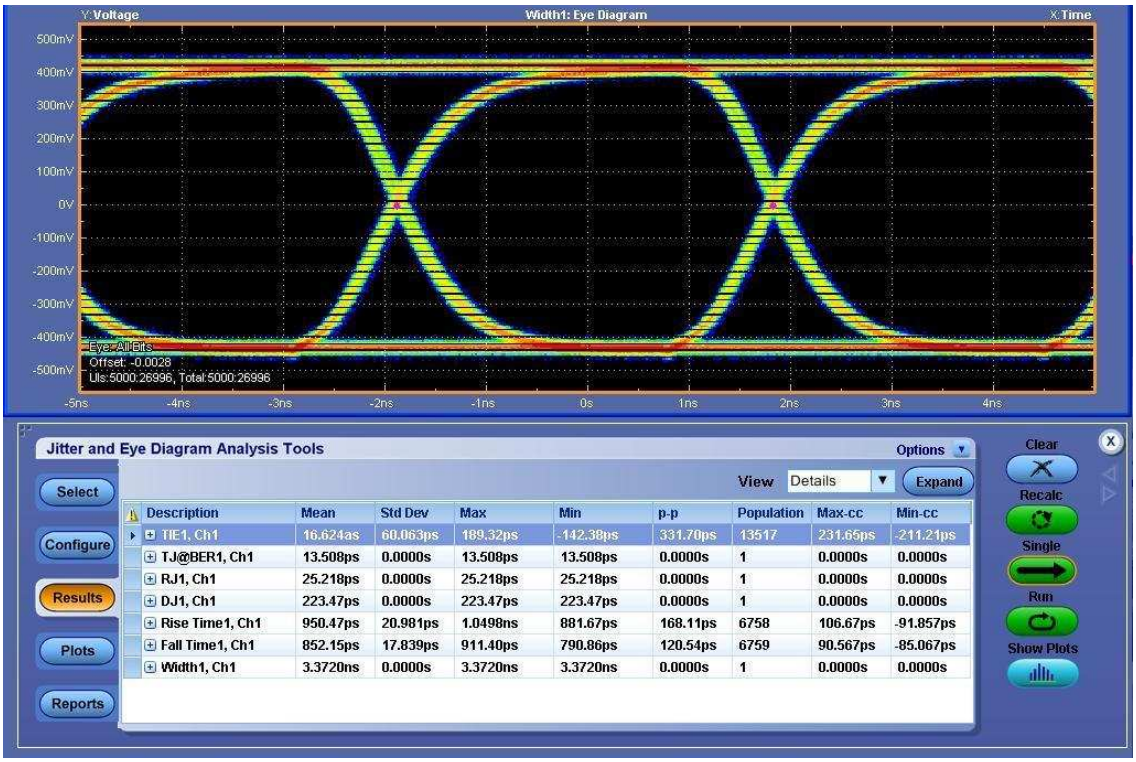


Figure 12. OUT0 (75 Ω) Alignment Jitter (AJ) and Rise / Fall Time at 270 Mbps
AJ = 13.508 ps, Tr / Tf = 950.47 / 852.15 ps

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7.2 Output Jitter Performance for Retimed Data

Figure 13 shows the output jitter performance of OUT1 under the following conditions:

- Input Signal Pattern: PRBS-15
- VID: 800 mVp-p
- Operating Frequency: 11.88 Gbps
- LMH1218 in Retimed mode with 15" FR4 Trace at Input, EQ = 0x80
- VDD = 2.5 V, T = 25°C

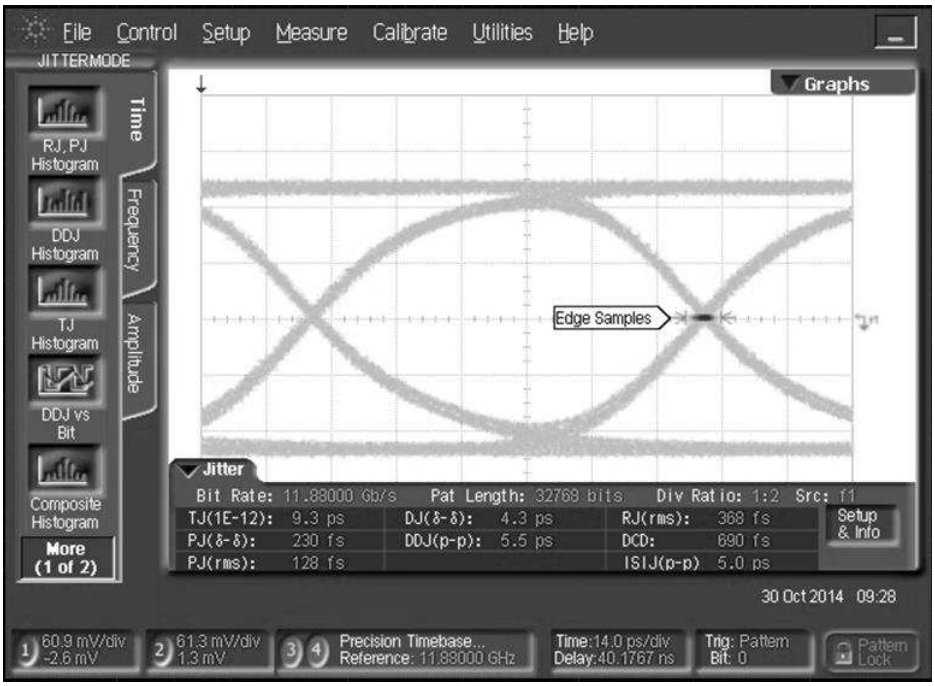


Figure 13. OUT1 (50 Ω) Output Jitter Measurement with 15" FR4 Input Trace TJ (E-12) = 9.3 ps

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8 Schematic

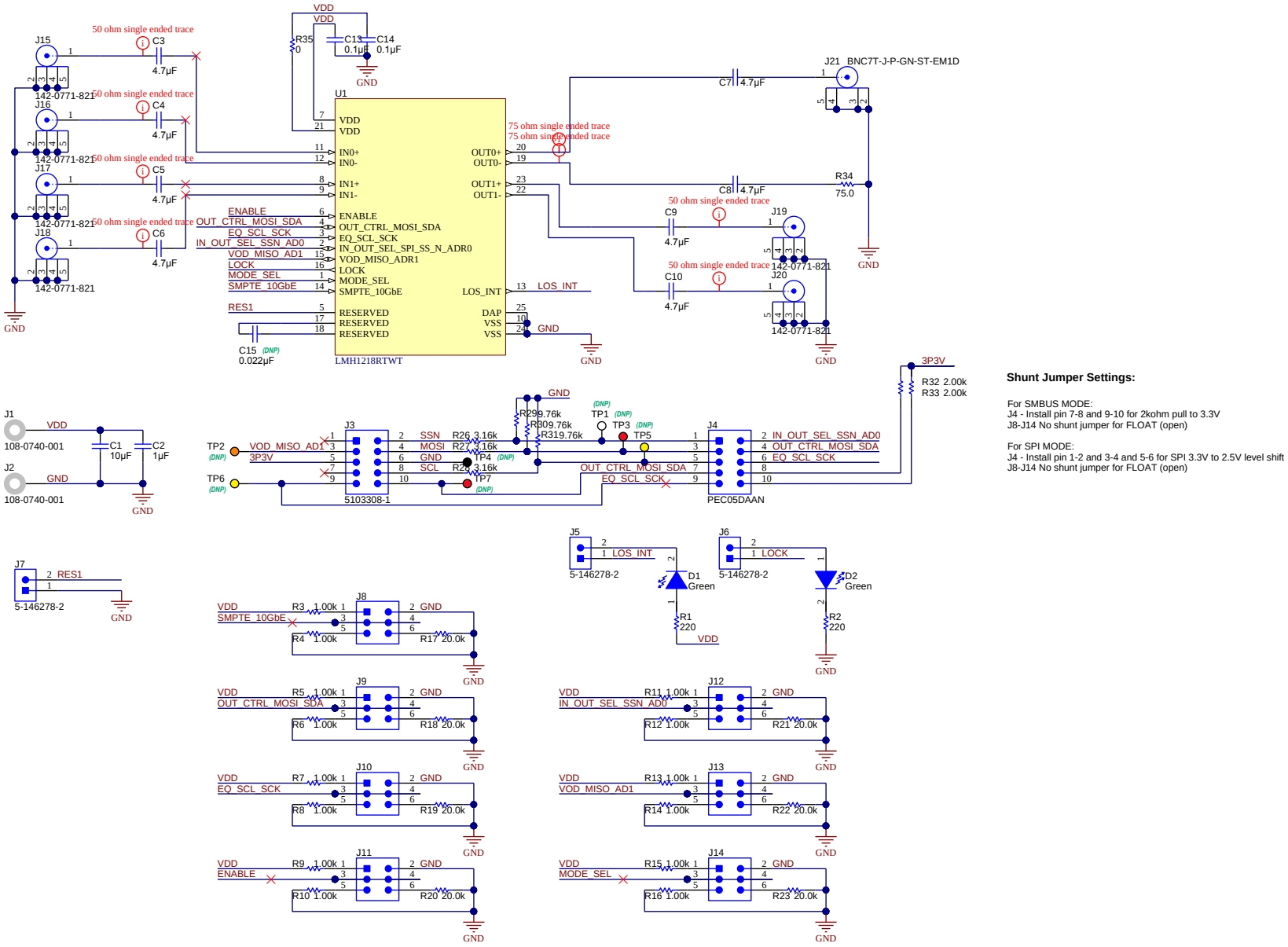


Figure 14. LMH1218EVM Schematic

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9 EVM Layout

Figure 15 and Figure 16 show the LMH1218EVM layout. The evaluation board controls signal integrity control settings via jumper pins.

The LMH1218EVM allows access to all input channels (IN0 and IN1) and output channels (OUT0 and OUT1). It is very compact and low power. The QFN package offers an exposed thermal pad to enhance electrical and thermal performance. This must be soldered to the copper landing on the PWB.

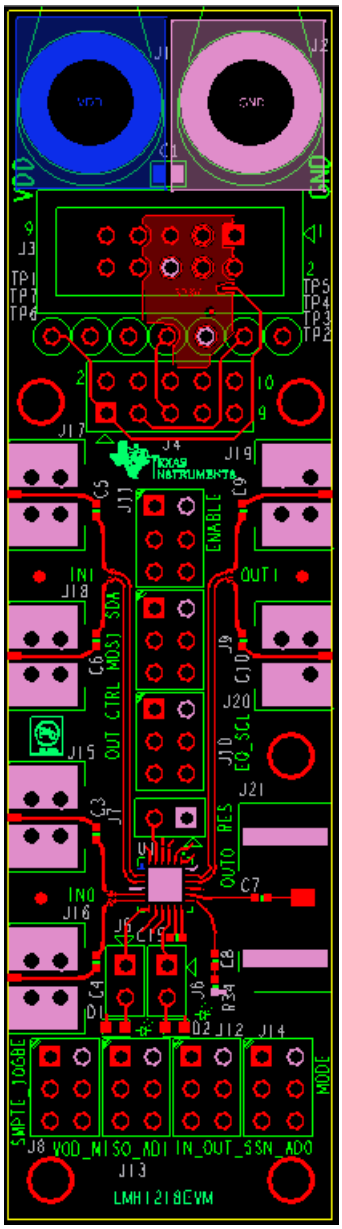


Figure 15. LMH1218EVM Top Layer

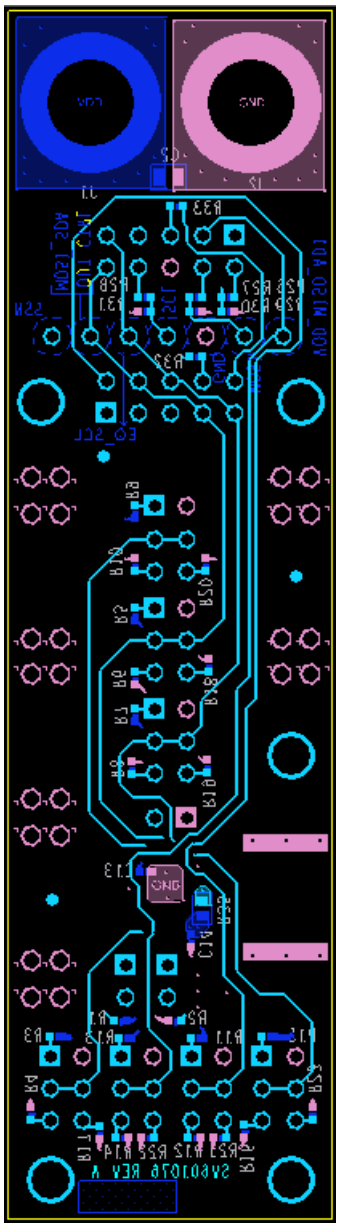


Figure 16. LMH1218EVM Bottom Layer

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10 Bill of Materials

Table 9. LMH1218EVM Bill of Materials

NO.	QTY.	DESIGNATOR	VALUE	FOOTPRINT	DESCRIPTION	COMMENTS
1	1	C1	10uF	0805_HV	CAP CER 10UF 16V 20% X5R 0805	
2	1	C2	1uF	0805_HV	CAP CER 1UF 16V 10% X5R 0805	
3	8	C3,C4,C5,C6,C7,C8,C9,C10	4.7uF	0402	CAP CER 4.7UF 6.3V 20% X5R 0402	
4	2	C13,C14	0.1uF	0402	CAP CER 0.1UF 6.3V 10% X5R 0402	
5	0	C15	0.022uF	0402	CAP CER 0.022UF 16V 10% X5R 0402	DNL
6	2	D1,D2	Green	LED_SML-LX0603GW	LED 565NM GRN DIFF 0603 SMD	
7	0	FID1,FID2,FID3,FID4,FID5	Fiducial10-30			DNL
8	5	H1,H2,H3,H4,H5	NY PMS 440 0025 PH	NY PMS 440 0025 PH	MACHINE SCREW PAN PHILLIPS 4-40	
9	5	H7,H8,H9,H10,H11	1902C	Keystone_1902C	HEX STANDOFF 4-40 NYLON 1/2"	
10	2	J1,J2	108-0740-001	Johnson_108-0740-001	CONN JACK BANANA UNINS PANEL MOU	
11	1	J3	5103308-1	CONN_5103308-1	CONN HEADER LOPRO STR 10POS GOLD	
12	1	J4	PEC05DAAN	CONN_PEC05DAAN	CONN HEADER .100 DUAL STR 10POS	
13	3	J5,J6,J7	5-146278-2	TE_5-146278-2	CONN HEADER BRKWY 2POS SLG .100	
14	7	J8,J9,J10,J11,J12,J13,J14	5-146254-3	TE_5-146254-3	CONN HEADER BRKWAY 6POS DL .100	
15	6	J15,J16,J17,J18,J19,J20	142-0771-821	Emerson_142-0771-821	CONN SMA JACK 50 OHM EDGE MNT	
16	1	J21	BNC7T-J-P-GN-ST-EM1D	SAMTEC_BNC7T-J-P-GN-ST-EM1D	BNC7T EDGE MOUNT DIE CAST STRAIGHT JACK	
17	2	R1,R2	220	0402	RES 220 OHM 1/16W 5% 0402 SMD	
18	14	R3,R4,R5,R6,R7,R8,R9,R10, R11,R12,R13,R14,R15,R16	1.00k	0402	RES 1.00K OHM 1/16W 1% 0402 SMD	
19	7	R17,R18,R19,R20,R21,R22, R23	20.0k	0402	RES 20.0K OHM 1/16W 1% 0402 SMD	
20	1	R34	75.0	0402	RES 75.0 OHM 1/16W 1% 0402 SMD	
21	3	R26,R27,R28	3.16k	0402	RES 3.16K OHM 1/16W 1% 0402 SMD	
22	3	R29,R30,R31	9.76k	0402	RES 9.76K OHM 1/16W 1% 0402 SMD	
23	2	R32,R33	2.00k	0402	RES 2.00K OHM 1/16W 1% 0402 SMD	
24	1	R35	0	0603	RES 0.0 OHM 1/10W JUMP 0603 SMD	
25	9	SH-J1,SH-J2,SH-J3,SH-J4,SH-J5,SH-J6,SH-J7,SH-J8,SH-J9	1x2	SNT-100-BK-G	SHUNT JUMPER .1" BLACK GOLD	
26	0	TP1	White	Keystone5002	TEST POINT PC MINI .040"D WHITE	DNL
27	0	TP2	Orange	Keystone5003	TEST POINT PC MINI .040"D ORANGE	DNL
28	0	TP3,TP7	Red	Keystone5000	TEST POINT PC MINI .040"D RED	DNL
29	0	TP4	Black	Keystone5001	TEST POINT PC MINI .040"D BLACK	DNL
30	0	TP5,TP6	Yellow	Keystone5004	TEST POINT PC MINI .040"D YELLOW	DNL
31	1	U1	LMH1218RTWT	RTW0024A	Ultra HD Low-Power SDI Reclocker and Cable Driver, RTW0024A	
32		SV601076 REVA BOARD PCB		305-PD-14-0659		

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Revision History

Changes from Original (January 2015) to A Revision	Page
• Changed to full document release.	2

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

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